Sony EMCS (M) Sdn Bhd has over the years attained an outstanding reputation in the global audio visual electronics industry. Our products have positively touched the lives of our precious consumers, pushing technology forward and making life more enjoyable and exciting. Sony EMCS (M) Sdn Bhd is the place for talented people to bring out their creativity and technological skills to the highest potential. Therefore we offer scholarships and career opportunities for students who can channel their unique talents and skills.

**Feel our dreams**

**Share our success**

**Walk our path**

**Eligibility**

- Malaysian citizen.
- Age below 25.
- Students currently in their second and third year of undergraduate study in IPTA/Public Universities.
- Outstanding academic achievements in school (SPM / O Level), pre-university (STPM / A Level / Matriculations), diploma and current degree qualifications with a minimum CGPA of 3.0.
- Proficient in English, hardworking, possess excellent academic achievements matched with positive personality traits and have outstanding extra-curricular activities.

**Scholarship Package**

- RM8,000 per annum.
- Students will be bonded and must be willing to serve SONY EMCS (M) SDN BHD for a specified period of time upon completion of studies.

**Field of Study**

- Scholarships are available for the following disciplines:
  - Bachelor of Engineering (Electrical & Electronics).
  - Bachelor of Engineering (Mechanical).
  - Other Engineering fields related to the above disciplines.

The completed application form with relevant documents should be sent to the address below by 24th July 2009:

**Human Resource Division**
**Attention to: Ms Farina Mohd Ramlan / Mr Soong Kim Wai**
Sony EMCS (Malaysia) Sdn Bhd
Lot 5, Jalan Kemajuan, Bangi Industrial Estate,
43650 Bandar Baru Bangi,
Selangor Darul Ehsan

* Enquiries can be directed to Ms Farina Mohd Ramlan (Farina.MohdRamlan@ap.sony.com) or Mr Soong Kim Wai (KimWai.Soong@ap.sony.com) at 03-89297113 / 03-89297507

Note: Please indicate “SCHOLARSHIP” on the top left corner of the envelope when submitting the application form.